

ABSTRACT OF THE DISCLOSURE

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An opening is formed in the center of a base on which an input/output electrode pattern is formed. Meanwhile, a plurality of bumps are formed on two opposing sides of an active element surface of the semiconductor integrated circuit so as to mount the semiconductor integrated circuit in the center of the opening. The semiconductor integrated circuit is connected to the electrode pattern on the base through the plurality of bumps by ultrasonic bonding. In this way, a small and thin piezoelectric device which has superior bonding characteristics of the semiconductor integrated circuit and the base, which are subjected to flip-chip bonding, and which endures mechanical shock, thermal stress, etc., can be obtained at reduced cost.